MSCSM70TAM05TPAG

Datasheet

Triple Phase Leg SiC MOSFET Power Module

April 2020

Microsemi

a Microchip company

Contents

1 Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

1.1 Revision 1.0

Revision 1.0 was published in April 2020. It is the first publication of this document.

2 Product Overview

The MSCSM70TAM05TPAG device is a triple phase leg 700 V/349 A full silicon carbide (SiC) power module.

Figure 1 • MSCSM70TAM05TPAG Electric Schematic

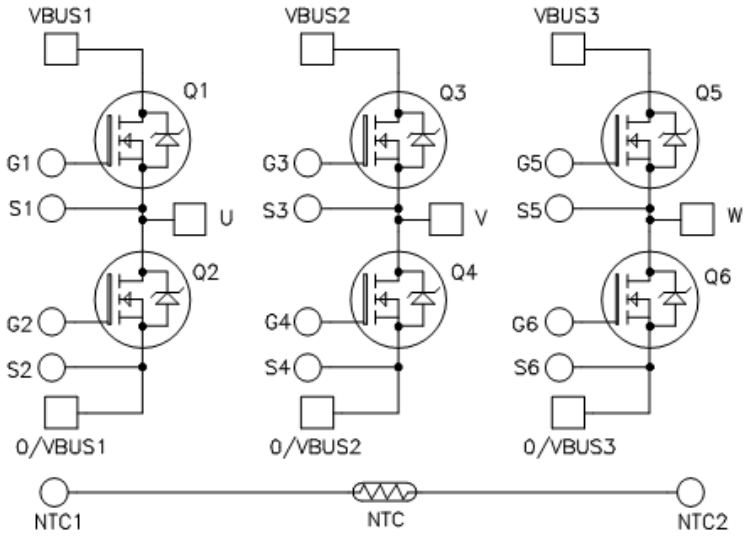
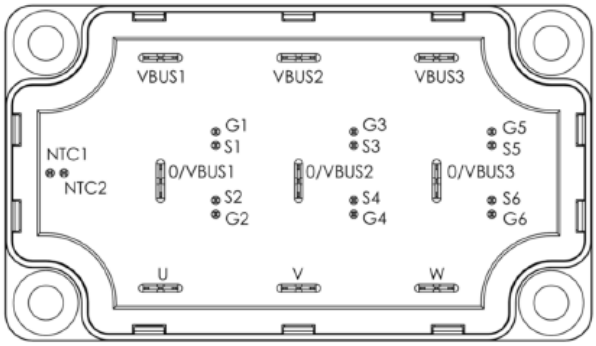


Figure 2 • MSCSM70TAM05TPAG Pinout Location



All ratings at T_J = 25 °C, unless otherwise specified.

Caution: These devices are sensitive to electrostatic discharge. Proper handling procedures should be followed.

2.1 Features

The following are key features of the MSCSM70TAM05TPAG device:

- SiC Power MOSFET
  - Low $R_{DS(on)}$
  - High-speed switching
  - Ultra low loss
- Very low stray inductance
- Kelvin source for easy drive
- Internal thermistor for temperature monitoring
- Aluminum nitride (AlN) substrate for improved thermal performance

2.2 Benefits

The following are benefits of the MSCSM70TAM05TPAG device:

- High-efficiency converter
- Outstanding performance at high-frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- Solderable terminals for power and signal, for easy PCB mounting
- Low profile
- RoHS compliant

2.3 Applications

The MSCSM70TAM05TPAG device is designed for the following applications:

- Uninterruptible power supplies
- Switched mode power supplies
- EV motor and traction drive
- Welding converters

3 Electrical Specifications

This section shows the electrical specifications of the MSCSM70TAM05TPAG device.

3.1 SiC MOSFET Characteristics (Per MOSFET)

The following table shows the absolute maximum ratings per SiC MOSFET of the MSCSM70TAM05TPAG device.

Table 1 • Absolute Maximum Ratings

Symbol	Parameter		Max Ratings	Unit
V_{DSS}	Drain-source voltage		700	V
I_D	Continuous drain current	T_C = 25 °C	349[1]	A
		T_C = 80 °C	278[1]	
I_{DM}	Pulsed drain current		700	
V_{GS}	Gate-source voltage		–10/25	V
R_{DSon}	Drain-source ON resistance		6.4	mΩ
P_D	Power dissipation	T_C = 25 °C	966	W

Note:

1. Specification of the SiC MOSFET device, but output current must be limited due to size of power connectors.

The following table shows the electrical characteristics per SiC MOSFET of the MSCSM70TAM05TPAG device.

Table 2 • Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V; V_{DS} = 700 V				300	µA
$R_{DS(on)}$	Drain-source on resistance	V_{GS} = 20 V I_D = 120 A	T_J = 25 °C		5	6.4	mΩ
			T_J = 175 °C		6.3		
$V_{GS(th)}$	Gate threshold voltage	V_{GS} = V_{DS}, I_D = 12 mA		1.9	2.4		V
I_{GSS}	Gate-source leakage current	V_{GS} = 20 V, V_{DS} = 0 V				300	nA

The following table shows the dynamic characteristics per SiC MOSFET of the MSCSM70TAM05TPAG device.

Table 3 • Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{iss}	Input capacitance	V_{GS} = 0 V V_{DS} = 700 V f = 1 MHz			13.5		nF
C_{oss}	Output capacitance				1.5		
C_{rss}	Reverse transfer capacitance				0.09		
Q_g	Total gate charge	V_{GS} = –5 V/20 V V_{Bus} = 470 V I_D= 120 A			645		nC
Q_{gs}	Gate-source charge				174		
Q_{gd}	Gate-drain charge				105		
$T_{d(on)}$	Turn-on delay time	V_{GS} = –5 V/20 V V_{Bus} = 400 V I_D = 240 A; T_J = 150 °C R_{Gon} = 9 Ω; R_{Goff} = 1.6 Ω			40		ns
T_r	Rise time				35		
$T_{d(off)}$	Turn-off delay time				50		
T_f	Fall time				20		
E_{on}	Turn on energy	Inductive switching V_{GS} = –5 V/20 V V_{Bus} = 400 V I_D = 160 A R_{Gon} = 9 Ω R_{Goff} = 1.6 Ω	T_J = 150 °C		1.96		mJ
E_{off}	Turn off energy		T_J = 150 °C		0.56		mJ
R_{Gint}	Internal gate resistance				1.9		Ω
R_{thJC}	Junction-to-case thermal resistance					0.155	°C/W

The following table shows the body diode ratings and characteristics per SiC MOSFET of the MSCSM70TAM05TPAG device.

Table 4 • Body Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{SD}	Diode forward voltage	V_{GS} = 0 V; I_{SD} = 120 A		3.4		V
		V_{GS} = –5V ; I_{SD} = 120 A		3.8		
t_{rr}	Reverse recovery time	I_{SD} = 120 A; V_{GS} = –5 V V_R = 400 V; d_{iF}/dt = 3000 A/µs		38		ns
Q_{rr}	Reverse recovery charge			954		nC
I_{rr}	Reverse recovery current			44		A

3.2 Thermal and Package Characteristics

The following table shows the package characteristics of the MSCSM70TAM05TPAG device.

Table 5 • Thermal and Package Characteristics

Symbol	Characteristic			Min	Max	Unit
V_{ISOL}	RMS isolation voltage, any terminal to case t = 1 min, 50 Hz/60 Hz			4000		V
T_J	Operating junction temperature range			–40	175	°C
T_{JOP}	Recommended junction temperature under switching conditions			–40	T_{Jmax}–25	
T_{STG}	Storage temperature range			–40	125	
T_C	Operating case temperature			–40	125	
Torque	Mounting torque	To heatsink	M6	3	5	N.m
Wt	Package weight				250	g

The following table shows the temperature sensor NTC (see application note *APT0406* on www.microsemi.com) of the MSCSM70TAM05TPAG device.

Table 6 • Temperature Sensor NTC

Symbol	Characteristic		Min	Typ	Max	Unit
R_{25}	Resistance at 25 °C			50		kΩ
$\Delta R_{25}/R_{25}$				5		%
$B_{25/85}$	T_{25} = 298.15 K			3952		K
ΔB/B		T_C = 100 °C		4		%

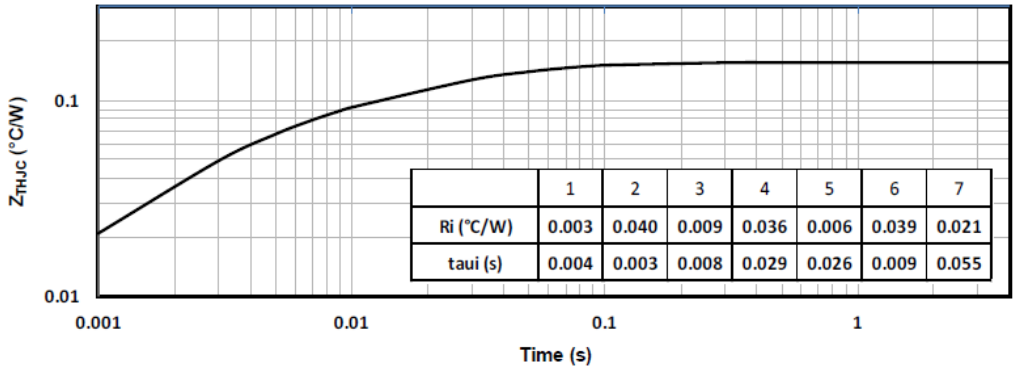
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature
R_T: Thermistor value at T

3.3 Typical SiC MOSFET Performance Curves

This sections shows the typical SiC MOSFET performance curves of the MSCSM70TAM05TPAG device.

Figure 3 • Maximum Thermal Impedance



	1	2	3	4	5	6	7
Ri (°C/W)	0.003	0.040	0.009	0.036	0.006	0.039	0.021
taui (s)	0.004	0.003	0.008	0.029	0.026	0.009	0.055

Figure 4 • Output Characteristics, T_J = 25 °C

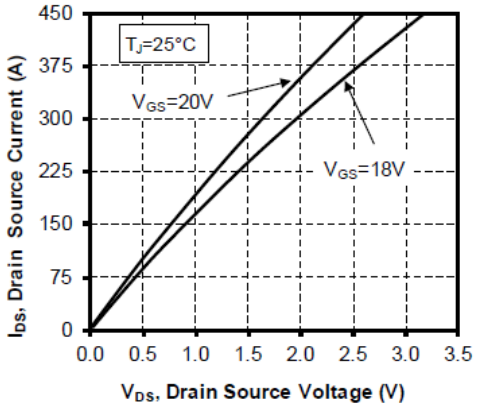


Figure 5 • Output Characteristics, T_J = 175 °C

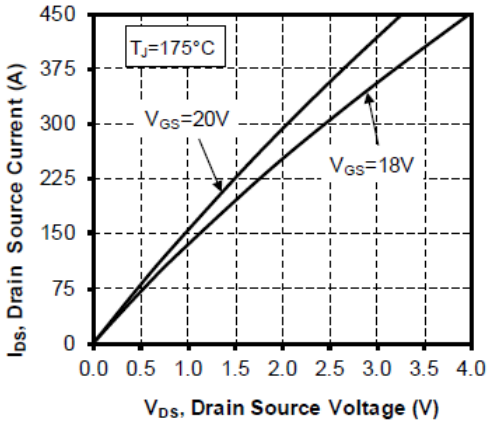


Figure 6 • Normalized $R_{DS(on)}$ vs. Temperature

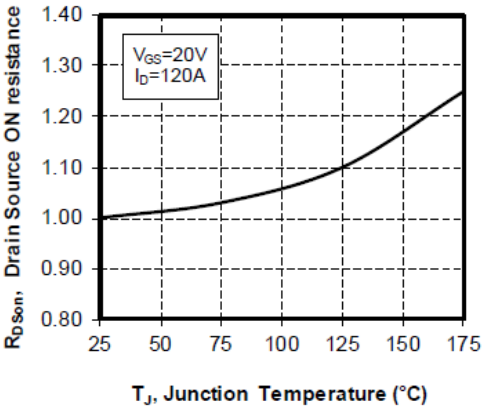


Figure 7 • Transfer Characteristics

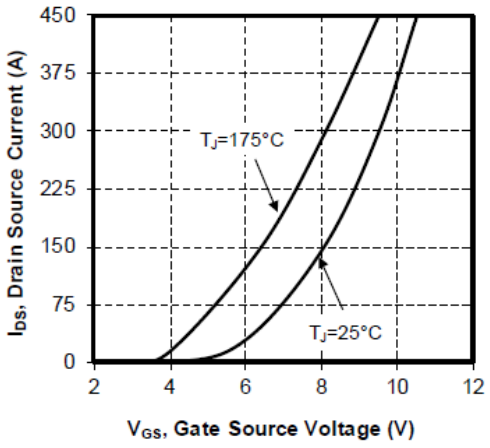


Figure 8 • Capacitance vs. Drain Source Voltage

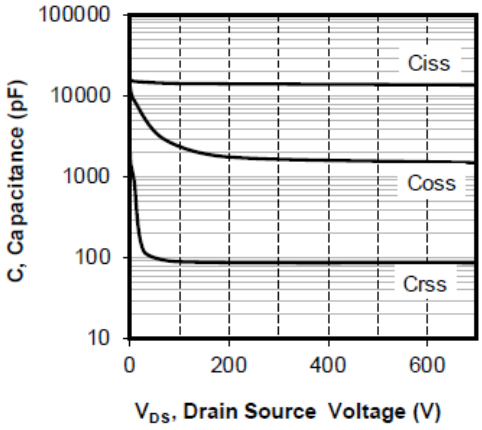


Figure 9 • Gate Charge vs. Gate Source Voltage

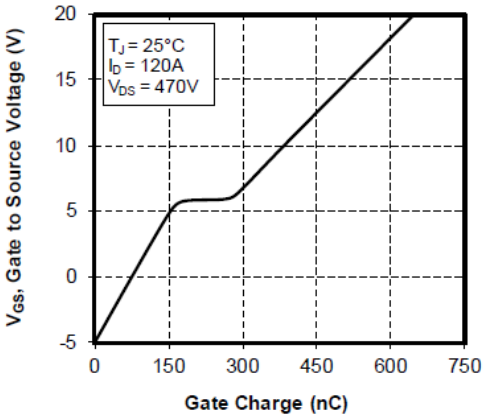


Figure 10 • Body Diode Characteristics, T_J = 25 °C

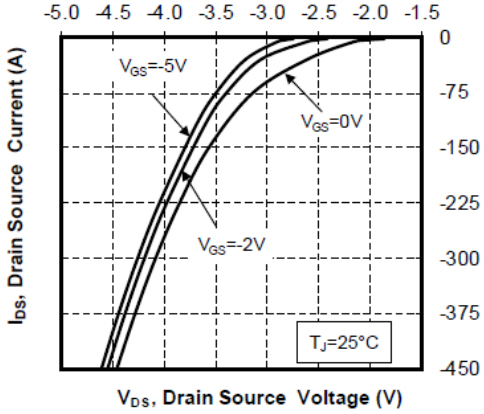


Figure 11 • 3rd Quadrant Characteristics, T_J = 25 °C

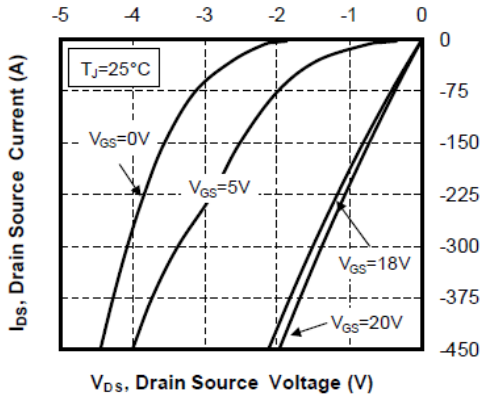


Figure 12 • Body Diode Characteristics, T_J = 175 °C

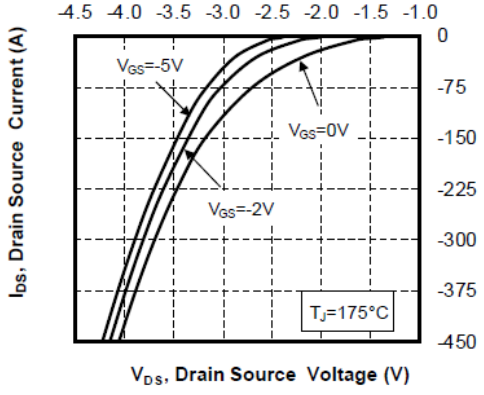


Figure 13 • 3rd Quadrant Characteristics, T_J = 175 °C

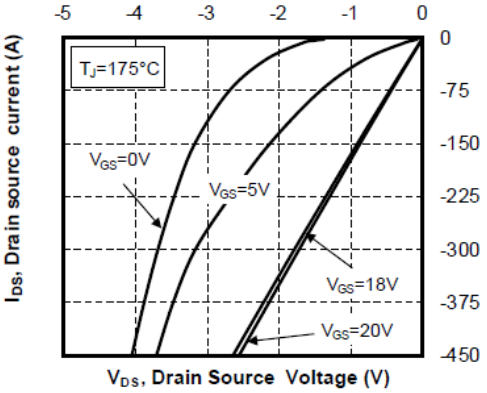


Figure 14 • Switching Energy vs. Current

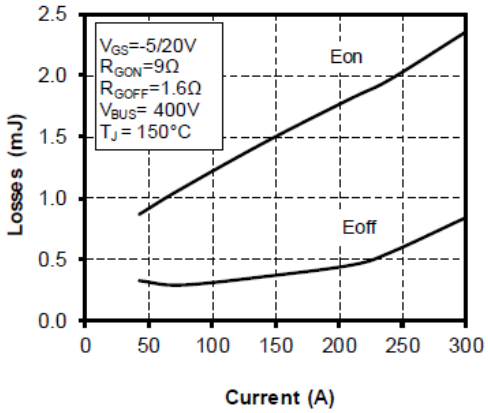


Figure 15 • Turn On Energy vs. Rg

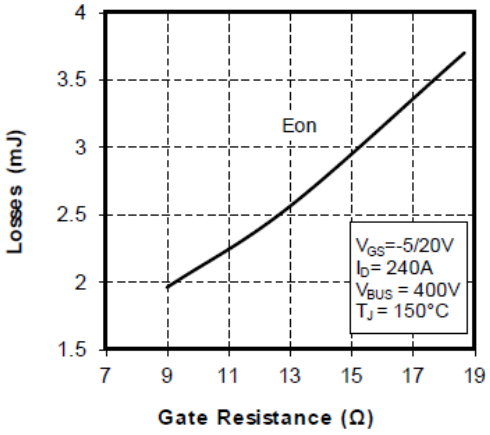


Figure 16 • Turn Off Energy vs. Rg

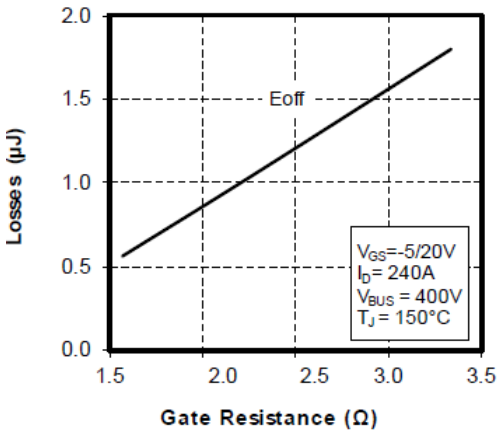
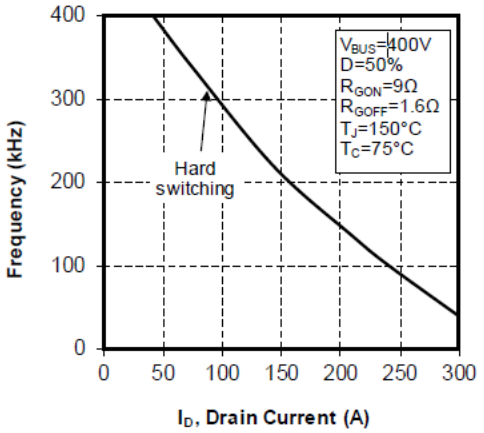


Figure 17 • Operating Frequency vs Drain Current



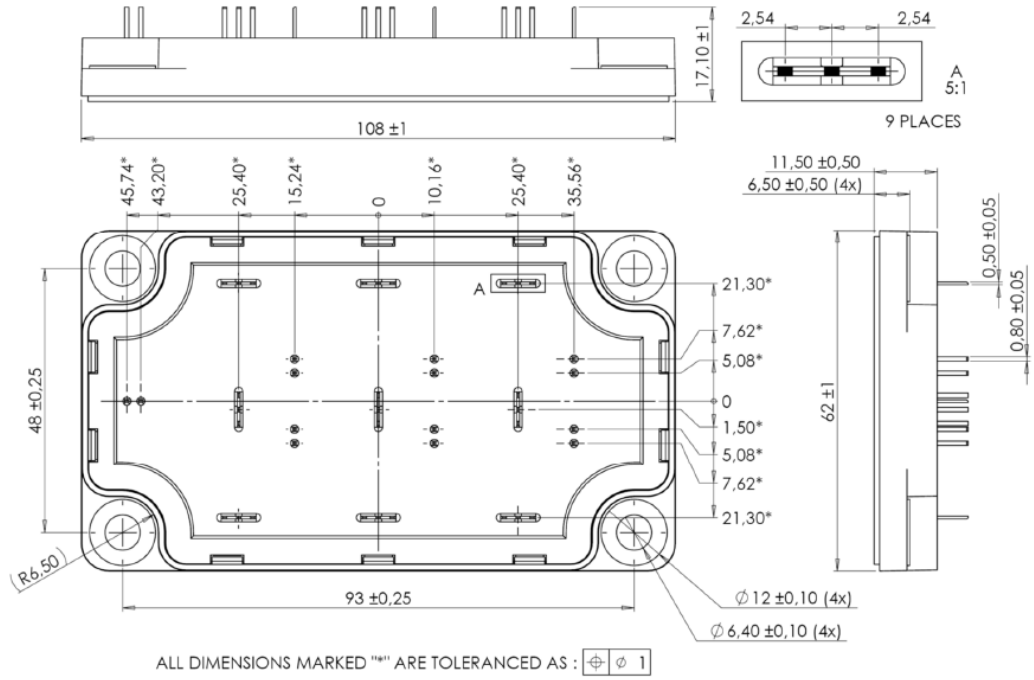
4 Package Specifications

This section shows the package specification of the MSCSM70TAM05TPAG device.

4.1 Package Outline Drawing

This section shows the package outline drawing of the MSCSM70TAM05TPAG device. The dimensions in the following figure are in millimeters.

Figure 18 • Package Outline Drawing



Note: See application note *1902 - Mounting Instructions for SP6-P (12 mm) Power Modules* on www.microsemi.com.

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